



Materials Declaration

Package	CSP BGA
Body Size	12 X 12
Ball Count	204
Option	Pb-Free
Ball Size	0.4

Molding Compound				
Item	% of Compound	Weight (g)	PPM	
Epoxy resin	7	1.34 E-02	36155	
SiO2 Filler	85	1.63 E-01	439026	
Phenol Resin	6.5	1.25 E-02	33573	
Carbon Black	0.5	9.60 E-04	2583	
Metal Hydroxide	1	1.92 E-03	5165	
Sub-Total		1.92 E-01	516501	

Molding Compound		
Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICPaes)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)

Laminate			
Item	% of Laminate	Weight (g)	PPM
BT-Epoxy	28	2.84 E-02	76361
Glass Fiber	25	2.53 E-02	68179
Copper	19	1.93 E-02	51816
Gold	11	1.12 E-02	29999
Nickel	7.8	7.91 E-03	21272
Solder Mask	9.35	9.48 E-03	25499
Brominated Compound	Confidential	Not Determined	
Sub-Total		1.02 E-01	273127

Die Attach Paste		
Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	ICP-AES

Solder Ball			
	% of Plating	Weight (g)	PPM
Sn	96.5	5.93 E-02	159644
Ag	3	1.84 E-03	4963
Cu	0.5	3.07 E-04	827
Sub-Total		6.15 E-02	165434

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	1.13 E-03	3048

Chip			
	% of Chip	Weight (g)	PPM
Si	100	1.41 E-02	37877

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	24	3.58 E-04	963
Ag Filler	76	1.13 E-03	3050
Sub-Total		1.49 E-03	4014

Package Totals	
Weight (g)	PPM
3.72 E-01	1000000

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Note: The information provided in this declaration are true to the best of ADI's knowledge
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Package	CSP BGA
Body Size	12 X 12
Ball Count	204
Option	SnPbAg
Ball Size	0.4

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Silica	90	1.70 E-01	460579
epoxy resin	4.8	9.04 E-03	24564
Phenol resin	3.91	7.37 E-03	20010
Antimony trioxide	0.69	1.30 E-03	3531
Bromine	0.6	1.13 E-03	3071
Sub-Total		1.88 E-01	511754

Molding Compound		
Item	PPM	Method
Cd	<5	BS EN 1122:2001B (ICPaes)

Laminate			
Item	% of Laminate	Weight (g)	PPM
BT-Epoxy	28	2.84 E-02	77111
Glass Fiber	25	2.53 E-02	68849
Copper	19	1.93 E-02	52325
Gold	11	1.12 E-02	30293
Nickel	7.8	7.91 E-03	21481
Solder Mask	9.35	9.48 E-03	25749
Brominated Compound	Confidential	Not Determined	
Sub-Total		1.02 E-01	275808

Die Attach Paste		
Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	ICP-AES

Solder Ball			
	% of Plating	Weight (g)	PPM
Sn	62	3.81 E-02	103576
Pb	36	2.21 E-02	60141
Ag	2	1.23 E-03	3341
Sub-Total		6.15 E-02	167058

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	1.13 E-03	3078

Chip			
	% of Chip	Weight (g)	PPM
Si	100	1.41 E-02	38249

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	23	3.43 E-04	932
Ag Filler	77	1.15 E-03	3121
Sub-Total		1.49 E-03	4053

Package Totals	
Weight (g)	PPM
3.68 E-01	1000000

STS-BC-C

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